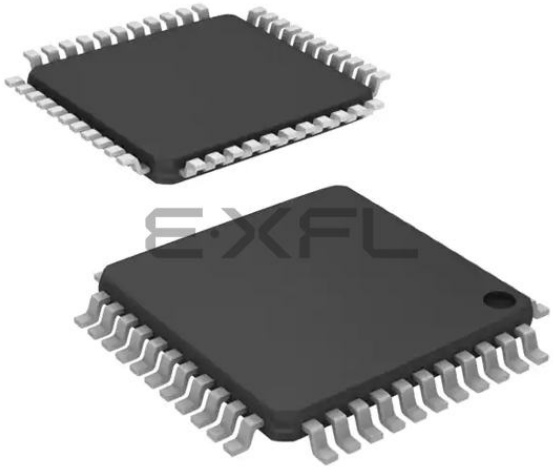

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Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep512mc204-i-pt

TABLE 4-1: CPU CORE REGISTER MAP FOR dsPIC33EPXXXMC20X/50X AND dsPIC33EPXXXGP50X DEVICES ONLY (CONTINUED)

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
SR	0042	OA	OB	SA	SB	OAB	SAB	DA	DC	IPL2	IPL1	IPL0	RA	N	OV	Z	C	0000
CORCON	0044	VAR	—	US<1:0>		EDT	DL<2:0>			SATA	SATB	SATDW	ACCSAT	IPL3	SFA	RND	IF	0020
MODCON	0046	XMODEN	YMODEN	—	—	BWM<3:0>				YWM<3:0>				XWM<3:0>				0000
XMODSRT	0048	XMODSRT<15:0>															—	0000
XMODEND	004A	XMODEND<15:0>															—	0001
YMODSRT	004C	YMODSRT<15:0>															—	0000
YMODEND	004E	YMODEND<15:0>															—	0001
XBREV	0050	BREN	XBREV<14:0>															0000
DISICNT	0052	—	—	DISICNT<13:0>														0000
TBLPAG	0054	—	—	—	—	—	—	—	—	TBLPAG<7:0>								0000
MSTRPR	0058	MSTRPR<15:0>																0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 7-4: INTCON2: INTERRUPT CONTROL REGISTER 2

R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
GIE	DISI	SWTRAP	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	INT2EP	INT1EP	INT0EP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **GIE:** Global Interrupt Enable bit
1 = Interrupts and associated IE bits are enabled
0 = Interrupts are disabled, but traps are still enabled

bit 14 **DISI:** DISI Instruction Status bit
1 = DISI instruction is active
0 = DISI instruction is not active

bit 13 **SWTRAP:** Software Trap Status bit
1 = Software trap is enabled
0 = Software trap is disabled

bit 12-3 **Unimplemented:** Read as ‘0’

bit 2 **INT2EP:** External Interrupt 2 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 1 **INT1EP:** External Interrupt 1 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 0 **INT0EP:** External Interrupt 0 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

12.1 Timer1 Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

12.1.1 KEY RESOURCES

- **"Timers"** (DS70362) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 16-13: IOCONx: PWMx I/O CONTROL REGISTER(2) (CONTINUED)

bit 1 **SWAP:** SWAP PWMxH and PWMxL Pins bit
1 = PWMxH output signal is connected to PWMxL pins; PWMxL output signal is connected to PWMxH pins
0 = PWMxH and PWMxL pins are mapped to their respective pins

bit 0 **OSYNC:** Output Override Synchronization bit
1 = Output overrides via the OVRDAT<1:0> bits are synchronized to the PWMx period boundary
0 = Output overrides via the OVDDAT<1:0> bits occur on the next CPU clock boundary

Note 1: These bits should not be changed after the PWMx module is enabled (PTEN = 1).

2: If the PWMLOCK Configuration bit (FOSCSEL<6>) is a '1', the IOCONx register can only be written after the unlock sequence has been executed.

REGISTER 16-16: LEBCONx: PWMx LEADING-EDGE BLANKING CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	BCH(1)	BCL(1)	BPHH	BPHL	BPLH	BPLL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PHR:** PWMxH Rising Edge Trigger Enable bit
1 = Rising edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxH

bit 14 **PHF:** PWMxH Falling Edge Trigger Enable bit
1 = Falling edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxH

bit 13 **PLR:** PWMxL Rising Edge Trigger Enable bit
1 = Rising edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxL

bit 12 **PLF:** PWMxL Falling Edge Trigger Enable bit
1 = Falling edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxL

bit 11 **FLTLEBEN:** Fault Input Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected Fault input
0 = Leading-Edge Blanking is not applied to selected Fault input

bit 10 **CLLEBEN:** Current-Limit Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected current-limit input
0 = Leading-Edge Blanking is not applied to selected current-limit input

bit 9-6 **Unimplemented:** Read as '0'

bit 5 **BCH:** Blanking in Selected Blanking Signal High Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is high
0 = No blanking when selected blanking signal is high

bit 4 **BCL:** Blanking in Selected Blanking Signal Low Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is low
0 = No blanking when selected blanking signal is low

bit 3 **BPHH:** Blanking in PWMxH High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is high
0 = No blanking when PWMxH output is high

bit 2 **BPHL:** Blanking in PWMxH Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is low
0 = No blanking when PWMxH output is low

bit 1 **BPLH:** Blanking in PWMxL High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is high
0 = No blanking when PWMxL output is high

bit 0 **BPLL:** Blanking in PWMxL Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is low
0 = No blanking when PWMxL output is low

Note 1: The blanking signal is selected via the BLANKSELx bits in the AUXCONx register.

REGISTER 17-17: INT1TMRH: INTERVAL 1 TIMER HIGH WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTTMR<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTTMR<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **INTTMR<31:16>:** High Word Used to Form 32-Bit Interval Timer Register (INT1TMR) bits

REGISTER 17-18: INT1TMRL: INTERVAL 1 TIMER LOW WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTTMR<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTTMR<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **INTTMR<15:0>:** Low Word Used to Form 32-Bit Interval Timer Register (INT1TMR) bits

REGISTER 21-26: CxTRmnCON: ECANx TX/RX BUFFER mn CONTROL REGISTER (m = 0,2,4,6; n = 1,3,5,7)

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENn	TXABTn	TXLARBn	TXERRn	TXREQn	RTRENn	TXnPRI1	TXnPRI0
bit 15							bit 8

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENm	TXABTm(1)	TXLARBm(1)	TXERRm(1)	TXREQm	RTRENm	TXmPRI1	TXmPRI0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 See Definition for bits<7:0>, Controls Buffer n

bit 7 **TXENm:** TX/RX Buffer Selection bit
1 = Buffer TRBn is a transmit buffer
0 = Buffer TRBn is a receive buffer

bit 6 **TXABTm:** Message Aborted bit(1)
1 = Message was aborted
0 = Message completed transmission successfully

bit 5 **TXLARBm:** Message Lost Arbitration bit(1)
1 = Message lost arbitration while being sent
0 = Message did not lose arbitration while being sent

bit 4 **TXERRm:** Error Detected During Transmission bit(1)
1 = A bus error occurred while the message was being sent
0 = A bus error did not occur while the message was being sent

bit 3 **TXREQm:** Message Send Request bit
1 = Requests that a message be sent; the bit automatically clears when the message is successfully sent
0 = Clearing the bit to '0' while set requests a message abort

bit 2 **RTRENm:** Auto-Remote Transmit Enable bit
1 = When a remote transmit is received, TXREQ will be set
0 = When a remote transmit is received, TXREQ will be unaffected

bit 1-0 **TXmPRI<1:0>:** Message Transmission Priority bits
11 = Highest message priority
10 = High intermediate message priority
01 = Low intermediate message priority
00 = Lowest message priority

Note 1: This bit is cleared when TXREQ is set.

Note: The buffers, SID, EID, DLC, Data Field, and Receive Status registers are located in DMA RAM.

BUFFER 21-7: ECAN™ MESSAGE BUFFER WORD 6

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 7							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 6							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 7<15:8>:** ECAN Message Byte 7 bits

bit 7-0 **Byte 6<7:0>:** ECAN Message Byte 6 bits

BUFFER 21-8: ECAN™ MESSAGE BUFFER WORD 7

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	FILHIT4(1)	FILHIT3(1)	FILHIT2(1)	FILHIT1(1)	FILHIT0(1)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-8 **FILHIT<4:0>:** Filter Hit Code bits(1)

Encodes number of filter that resulted in writing this buffer.

bit 7-0 **Unimplemented:** Read as ‘0’

Note 1: Only written by module for receive buffers, unused for transmit buffers.

25.3 Op Amp/Comparator Registers

REGISTER 25-1: CMSTAT: OP AMP/COMPARATOR STATUS REGISTER

R/W-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
PSIDL	—	—	—	C4EVT(1)	C3EVT(1)	C2EVT(1)	C1EVT(1)
bit 15							bit 8

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	C4OUT(2)	C3OUT(2)	C2OUT(2)	C1OUT(2)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PSIDL:** Comparator Stop in Idle Mode bit
1 = Discontinues operation of all comparators when device enters Idle mode
0 = Continues operation of all comparators in Idle mode

bit 14-12 **Unimplemented:** Read as '0'

bit 11 **C4EVT:** Op Amp/Comparator 4 Event Status bit(1)
1 = Op amp/comparator event occurred
0 = Op amp/comparator event did not occur

bit 10 **C3EVT:** Comparator 3 Event Status bit(1)
1 = Comparator event occurred
0 = Comparator event did not occur

bit 9 **C2EVT:** Comparator 2 Event Status bit(1)
1 = Comparator event occurred
0 = Comparator event did not occur

bit 8 **C1EVT:** Comparator 1 Event Status bit(1)
1 = Comparator event occurred
0 = Comparator event did not occur

bit 7-4 **Unimplemented:** Read as '0'

bit 3 **C4OUT:** Comparator 4 Output Status bit(2)
When CPOL = 0:
1 = VIN+ > VIN-
0 = VIN+ < VIN-
When CPOL = 1:
1 = VIN+ < VIN-
0 = VIN+ > VIN-

bit 2 **C3OUT:** Comparator 3 Output Status bit(2)
When CPOL = 0:
1 = VIN+ > VIN-
0 = VIN+ < VIN-
When CPOL = 1:
1 = VIN+ < VIN-
0 = VIN+ > VIN-

Note 1: Reflects the value of the of the CEVT bit in the respective Op Amp/Comparator Control register, CMxCON<9>.

2: Reflects the value of the COUT bit in the respective Op Amp/Comparator Control register, CMxCON<8>.

REGISTER 26-2: CRCCON2: CRC CONTROL REGISTER 2

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	DWIDTH4	DWIDTH3	DWIDTH2	DWIDTH1	DWIDTH0
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	PLEN4	PLEN3	PLEN2	PLEN1	PLEN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-8 **DWIDTH<4:0>:** Data Width Select bits
These bits set the width of the data word (DWIDTH<4:0> + 1).

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **PLEN<4:0>:** Polynomial Length Select bits
These bits set the length of the polynomial (Polynomial Length = PLEN<4:0> + 1).

27.2 User ID Words

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices contain four User ID Words, located at addresses, 0x800FF8 through 0x800FFE. The User ID Words can be used for storing product information such as serial numbers, system manufacturing dates, manufacturing lot numbers and other application-specific information.

The User ID Words register map is shown in Table 27-3.

TABLE 27-3: USER ID WORDS REGISTER MAP

File Name	Address	Bits 23-16	Bits 15-0
FUID0	0x800FF8	—	UID0
FUID1	0x800FFA	—	UID1
FUID2	0x800FFC	—	UID2
FUID3	0x800FFE	—	UID3

Legend: — = unimplemented, read as '1'.

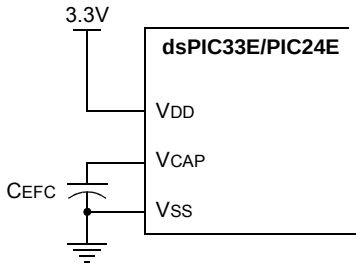
27.3 On-Chip Voltage Regulator

All of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices power their core digital logic at a nominal 1.8V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. A low-ESR (less than 1 Ohm) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 27-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 30-5 located in **Section 30.0 "Electrical Characteristics"**.

Note:	It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

FIGURE 27-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to Table 30-5 located in **Section 30.1 "DC Characteristics"** for the full operating ranges of VDD and VCAP.

2: It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 1.8V when VDD ≥ VDDMIN.

27.4 Brown-out Reset (BOR)

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage, VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT Time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, then a nominal delay of TFSCM is applied. The total delay in this case is TFSCM. Refer to Parameter SY35 in Table 30-22 of **Section 30.0 "Electrical Characteristics"** for specific TFSCM values.

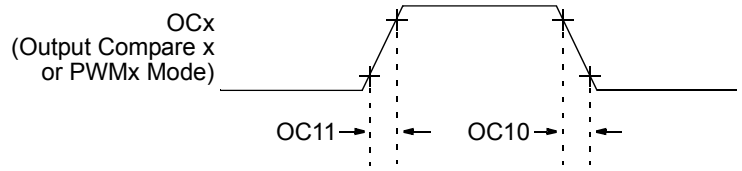
The BOR status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle modes and resets the device should VDD fall below the BOR threshold voltage.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles(2)	Status Flags Affected
52	MUL	MUL.SS Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * signed(Ws)	1	1	None
		MUL.SS Wb,Ws,Acc(1)	Accumulator = signed(Wb) * signed(Ws)	1	1	None
		MUL.SU Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb,Ws,Acc(1)	Accumulator = signed(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb,#lit5,Acc(1)	Accumulator = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.US Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * signed(Ws)	1	1	None
		MUL.US Wb,Ws,Acc(1)	Accumulator = unsigned(Wb) * signed(Ws)	1	1	None
		MUL.UU Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(Ws)	1	1	None
		MUL.UU Wb,#lit5,Acc(1)	Accumulator = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb,Ws,Acc(1)	Accumulator = unsigned(Wb) * unsigned(Ws)	1	1	None
		MULW.SS Wb,Ws,Wnd	Wnd = signed(Wb) * signed(Ws)	1	1	None
		MULW.SU Wb,Ws,Wnd	Wnd = signed(Wb) * unsigned(Ws)	1	1	None
		MULW.US Wb,Ws,Wnd	Wnd = unsigned(Wb) * signed(Ws)	1	1	None
		MULW.UU Wb,Ws,Wnd	Wnd = unsigned(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.SU Wb,#lit5,Wnd	Wnd = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb,#lit5,Wnd	Wnd = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL f	W3:W2 = f * WREG	1	1	None

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

FIGURE 30-7: OUTPUT COMPARE x MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-27: OUTPUT COMPARE x MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See Parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See Parameter DO31

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 30-8: OCx/PWMx MODULE TIMING CHARACTERISTICS

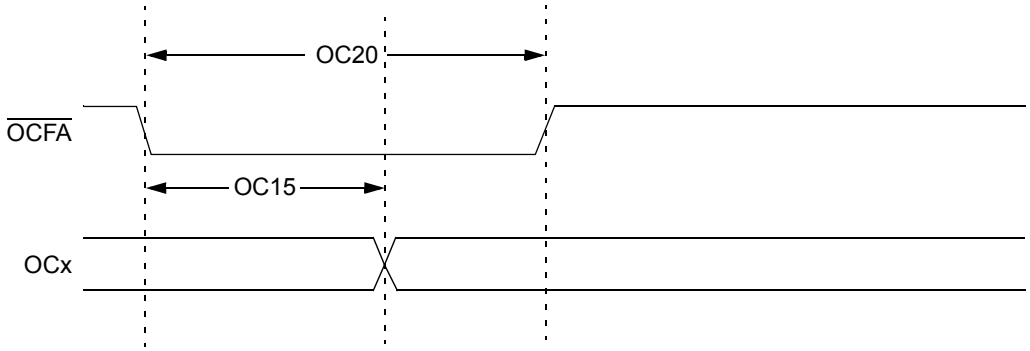


TABLE 30-28: OCx/PWMx MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWMx I/O Change	—	—	TCY + 20	ns	
OC20	TFLT	Fault Input Pulse Width	TCY + 20	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 30-20: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

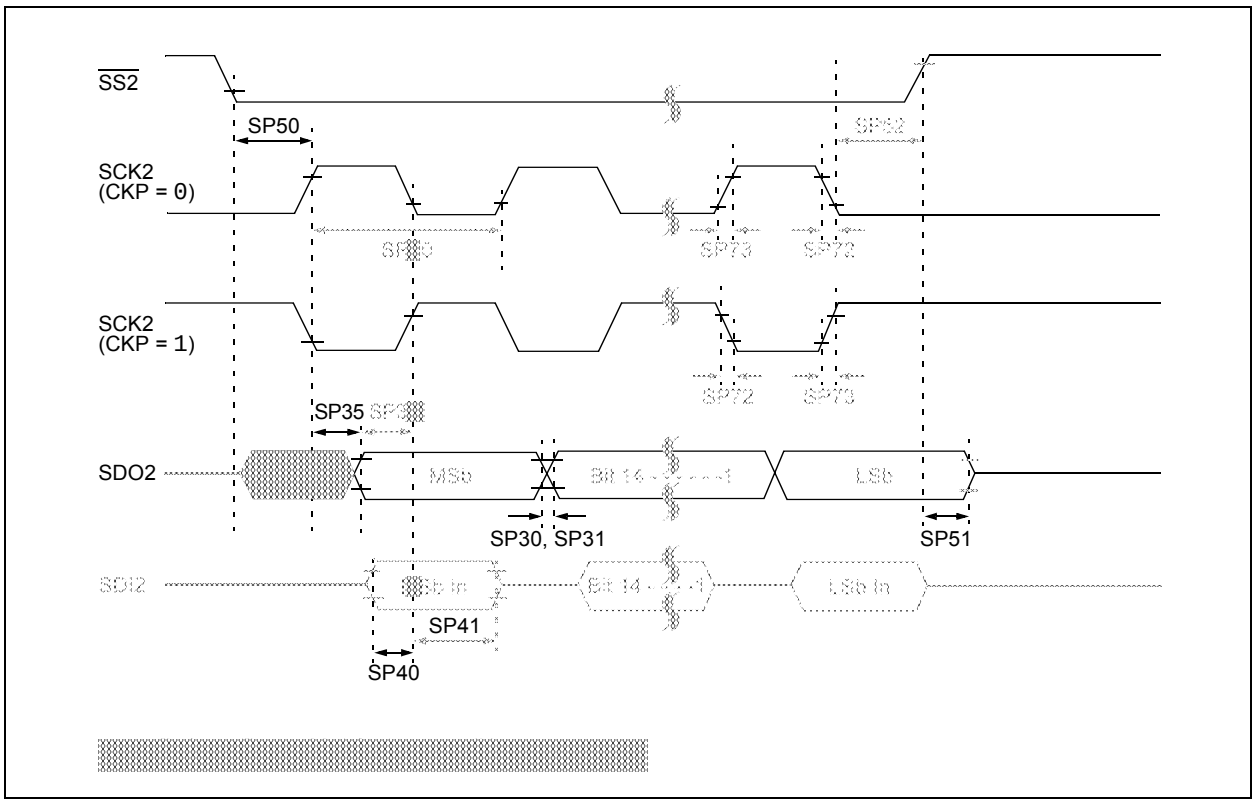
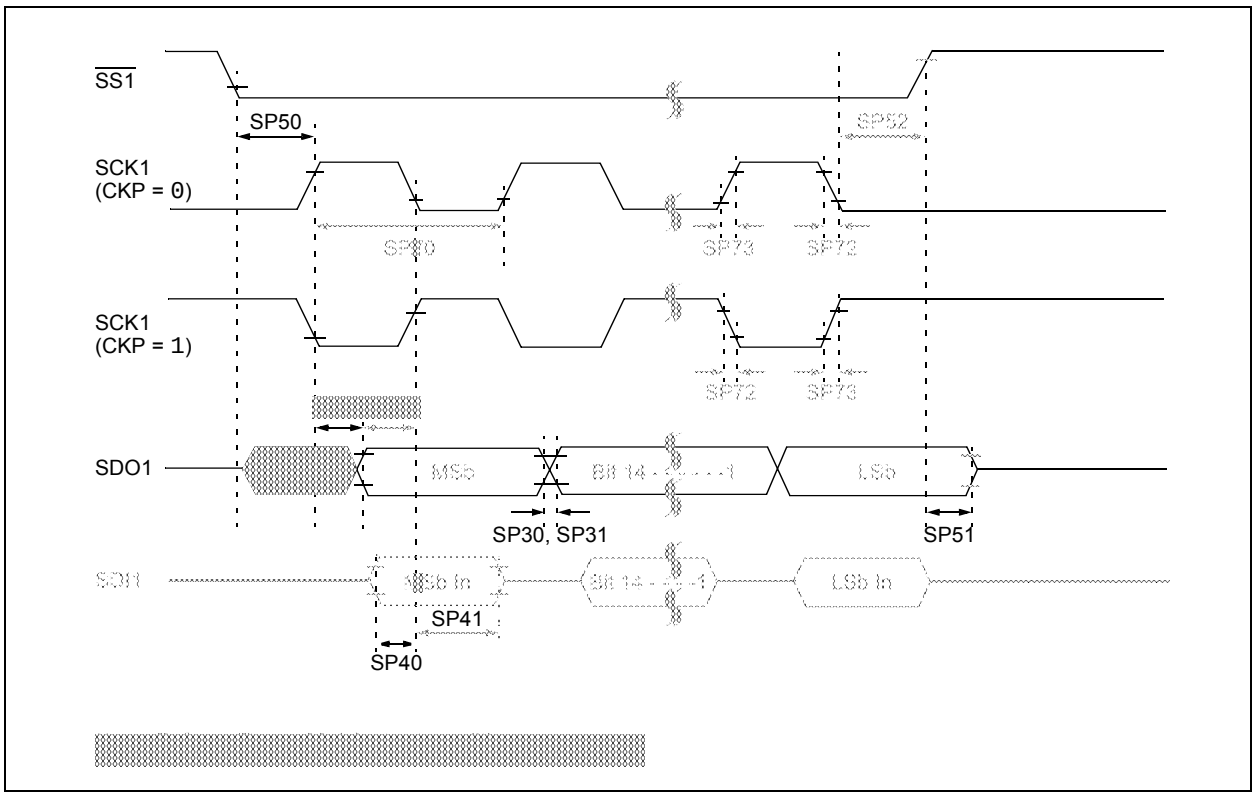
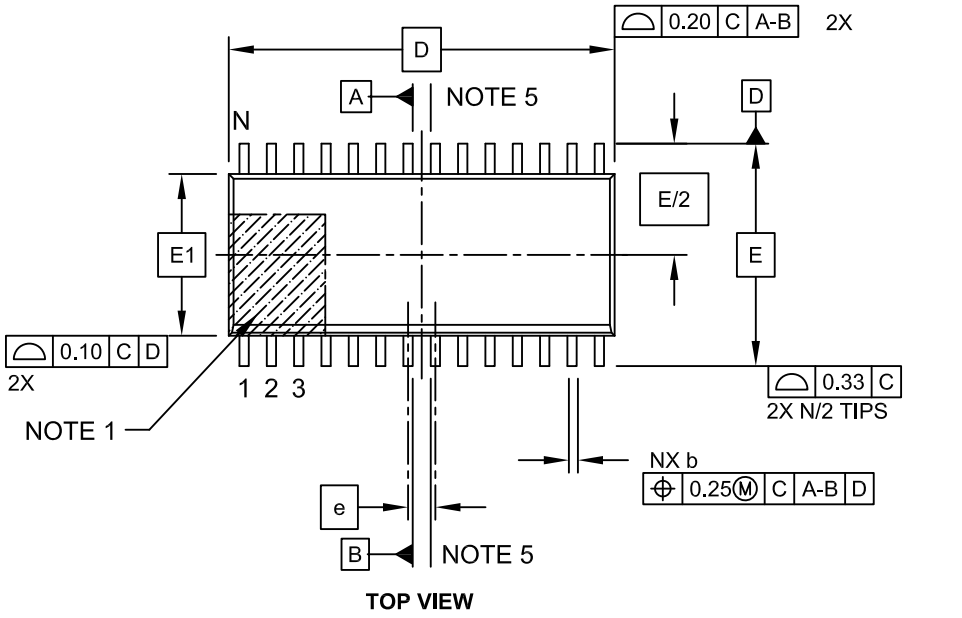


FIGURE 30-29: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS

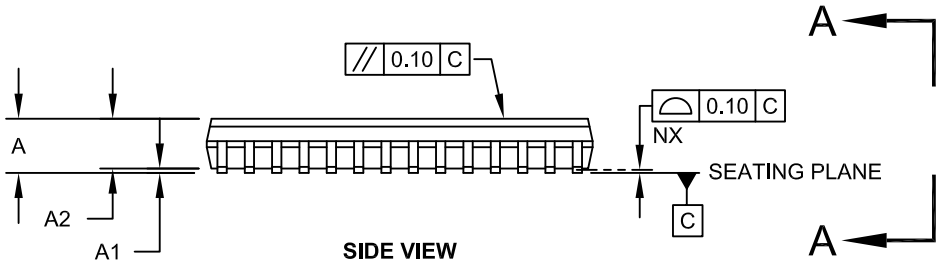


28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

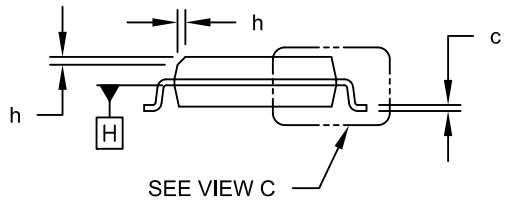
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW



VIEW A-A

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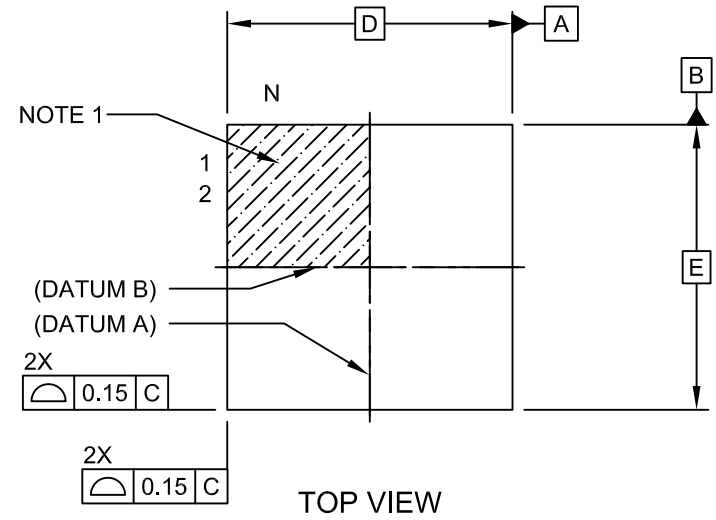
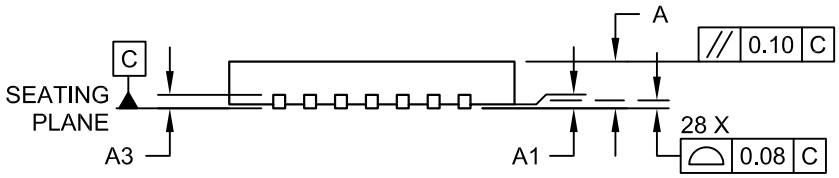
28-Lead Plastic Quad Flat, No Lead Package (MM) - 6x6x0.9mm Body [QFN-S] With 0.40 mm Terminal Length

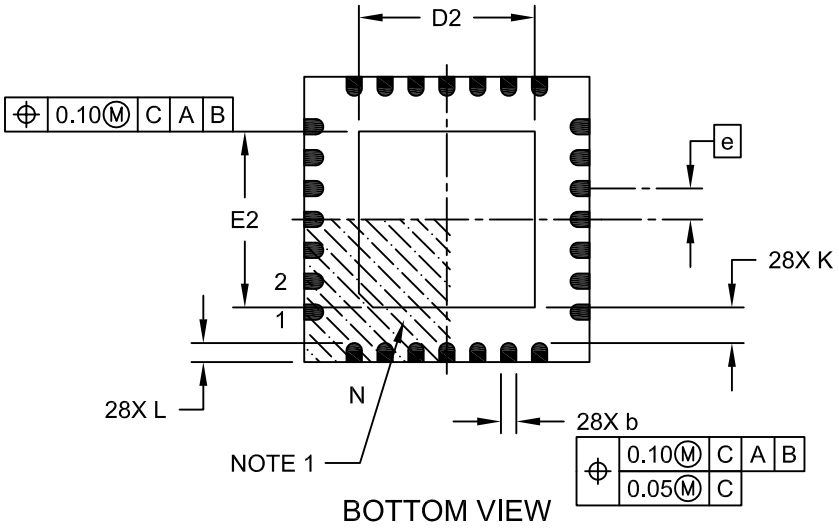
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW



BOTTOM VIEW

Microchip Technology Drawing C04-124C Sheet 1 of 2

Revision H (August 2013)

This revision includes minor typographical and formatting changes throughout the text.

Other major changes are referenced by their respective section in Table A-6.

TABLE A-6: MAJOR SECTION UPDATES

Section Name	Update Description
Cover Section	• Adds Peripheral Pin Select (PPS) to allow Digital Function Remapping and Change Notification Interrupts to Input/Output section • Adds heading information to 64-Pin TQFP
Section 4.0 "Memory Organization"	• Corrects Reset values for ANSELE, TRISF, TRISC, ANSELC and TRISA • Corrects address range from 0x2FFF to 0x7FFF • Corrects DSRPAG and DSWPAG (now 3 hex digits) • Changes Call Stack Frame from <15:1> to PC<15:0> • Word length in Figure 4-20 is changed to 50 words for clarity
Section 5.0 "Flash Program Memory"	• Corrects descriptions of NVM registers
Section 9.0 "Oscillator Configuration"	• Removes resistor from Figure 9-1 • Adds Fast RC Oscillator with Divide-by-16 (FRCDIV16) row to Table 9-1 • Removes incorrect information from ROI bit in Register 9-2
Section 14.0 "Input Capture"	• Changes 31 user-selectable Trigger/Sync interrupts to 19 user-selectable Trigger/Sync interrupts • Corrects ICTSEL<12:10> bits (now ICTSEL<2:0>)
Section 17.0 "Quadrature Encoder Interface (QEI) Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"	• Corrects QCAPEN bit description
Section 19.0 "Inter-Integrated Circuit™ (I^2C™)"	• Adds note to clarify that 100kbit/sec operation of I^2C is not possible at high processor speeds
Section 22.0 "Charge Time Measurement Unit (CTMU)"	• Clarifies Figure 22-1 to accurately reflect peripheral behavior
Section 23.0 "10-Bit/12-Bit Analog-to-Digital Converter (ADC)"	• Correct Figure 23-1 (changes CH123x to CH123Sx)
Section 24.0 "Peripheral Trigger Generator (PTG) Module"	• Adds footnote to Register 24-1 (In order to operate with CVRSS=1, at least one of the comparator modules must be enabled.
Section 25.0 "Op Amp/ Comparator Module"	• Adds note to Figure 25-3 (In order to operate with CVRSS=1, at least one of the comparator modules must be enabled) • Adds footnote to Register 25-2 (COE is not available when OPMODE (CMxCON<10>) = 1)
Section 27.0 "Special Features"	• Corrects the bit description for FNOSC<2:0>
Section 30.0 "Electrical Characteristics"	• Corrects 512K part power-down currents based on test data • Corrects WDT timing limits based on LPRC oscillator tolerance
Section 31.0 "High-Temperature Electrical Characteristics"	• Adds Table 31-5 (DC Characteristics: Idle Current (I_{IDLE})

P

Q

R

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Printed on recycled paper.

ISBN: 9781620773949

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